264M-BB-DB9 TEC High Power LaserMount



Active Cooling

The 264M TEC LaserMount was designed for high power devices needing active temperature control. With its large heat sink and integrated fan, the 264 can handle high thermal loads and broad temperature ranges.

Thermistor Control

The mount uses a 10K thermistor for temperature feedback.

- Metric
- Bread board cold plate
- TEC controlled
- 30W capacity at 25°C

Bread Board Cold Plate

Using a bread board hole pattern found on optical tables, the 264-BB-DB9 provides a grid of threaded metric (M2.5) holes for maximum flexibility in mounting your thermal load. Be it a laser device, optic platform, or other application, the bread board configuration gives you excellent long term flexibility in how to mount your loads.

Device Cover

Beyond the mount itself, the 264 works with our optional device cover:



The 260-C cover enhances the stability of the laser by minimizing the impact of ambient air currents.

Specifications

Laser Package Supported	Various, contact factory
Thermal Capacity	30W At 0°C delta from ambient, 25°C ambient temperature
Cold plate	2.2" x 2.7" solid copper, nickel plated M2.5 threaded holes on 6.25mm centers
Input connectors	
Laser Diode	DB9, male
Mount TEC	DB-15, male
Temperature Control	
Temperature Range (°C)	+15 to +85
Sensor Type	10kΩ Thermistor
TE Module Imax (A)	7.4
TE Module Vmax (V)	16.4
TE Module Qmax (W)	78
General	
Size (H x W x D) [in(mm)]	3.0 (76.2) x 4.5 (114.3) x 6.0 (152.4)
Mounting holes	½-20 x 4